

09/890455

7-17-02 PB

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
 Hiroaki INOUE et al. : Attn: BOX PCT
 Serial No. NEW : Docket No. 2001_1094A
 Filed August 1, 2001 :

ELECTROLESS PLATING LIQUID AND METHOD
 OF FORMING INTERCONNECTION USING SUCH
 AN ELECTROLESS PLATING LIQUID
 [Corresponding to PCT/JP00/09099
 Filed December 21, 2000]

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
 Washington, DC 20231

Sir:

Prior to calculating the filing fee, please amend the above-identified application as follows:

IN THE SPECIFICATION

Page 1, immediately after the title, please insert:

This application is a 371 of PCT/JP00/09099 filed December 21, 2000.

IN THE CLAIMS

Please amend claim 5 as follows:

1. (Amended) A method of forming a copper interconnection on a semiconductor device, characterized by the steps of forming an auxiliary seed layer for reinforcing a copper seed layer in an interconnection groove defined in a surface of the semiconductor device using an electroless copper plating liquid containing dihydric copper ions, a complexing agent, and an aldehyde acid, and performing an electrolytic plating process using the seed layer including said auxiliary seed